

High Temperature Silicon Carbide Power Schottky Diode

V_{RRM} = 650 V $I_{F (Tc=25^{\circ}C)}$ = 8 A Q_{C} = 20 nC

Features

- 650 V Schottky rectifier
- 210 °C maximum operating temperature
- Electrically isolated base-plate
- Zero reverse recovery charge
- Superior surge current capability
- Positive temperature coefficient of V_F
- Temperature independent switching behavior
- Lowest figure of merit Q_C/I_F
- Available screened to Mil-PRF-19500

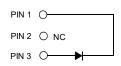
Advantages

- High temperature operation
- Improved circuit efficiency (Lower overall cost)
- · Low switching losses
- Ease of paralleling devices without thermal runaway
- · Smaller heat sink requirements
- Industry's lowest reverse recovery charge
- Industry's lowest device capacitance
- Ideal for output switching of power supplies
- Best in class reverse leakage current at operating temperature

Package

RoHS Compliant





TO - 257 (Isolated Base-plate Hermetic Package)

Applications

- Down Hole Oil Drilling
- Geothermal Instrumentation
- Solenoid Actuators
- General Purpose High-Temperature Switching
- Amplifiers
- Solar Inverters
- Switched-Mode Power Supply (SMPS)
- Power Factor Correction (PFC)

Maximum Ratings at T_j = 210 °C, unless otherwise specified

Parameter	Symbol	Conditions	Values	Unit
Repetitive peak reverse voltage	V_{RRM}		650	V
Continuous forward current	I _F	T _C = 25 °C	8	Α
Continuous forward current	I _F	T _C ≤ 190 °C	2.5	Α
RMS forward current	I _{F(RMS)}	T _C ≤ 190 °C	4.3	Α
Surge non-repetitive forward current, Half Sine Wave	$I_{F,SM}$	T_{C} = 25 °C, t_{P} = 10 ms	32	А
Non-repetitive peak forward current	$I_{F,max}$	T _C = 25 °C, t _P = 10 μs	120	Α
l ² t value	∫i² dt	T_{C} = 25 °C, t_{P} = 10 ms	5	A^2S
Power dissipation	P _{tot}	T _C = 25 °C	66	W
Operating and storage temperature	T _j , T _{stg}		-55 to 210	°C

Electrical Characteristics at T_j = 210 °C, unless otherwise specified

Parameter	Cymahal	Conditions mi		Values		l lmi4	
Parameter	Symbol			min.	typ.	max.	Unit
Diode forward voltage	V_{F}	I _F = 2.5 A, T _j = 25 °C			1.3		
		$I_F = 2.5 \text{ A}, T_j = 210 \text{ °C}$		2.0		V	
Reverse current	I _R	$V_R = 650 \text{ V}, T_j = 25 ^{\circ}\text{C}$		1	5	μΑ	
		$V_R = 650 \text{ V}, T_j = 210 ^{\circ}\text{C}$		10	100		
Total capacitive charge	Q_{C}	$I_F \le I_{F,MAX}$ $dI_F/dt = 200 \text{ A/µs}$	V _R = 400 V		20		nC
Switching time	t _s	$T_i = 210 \text{ eV}$	V _R = 400 V		< 25		ns
	С	$V_R = 1 \text{ V, } f = 1 \text{ MHz, } T_j = 25 \text{ °C}$ $V_R = 400 \text{ V, } f = 1 \text{ MHz, } T_j = 25 \text{ °C}$		274		pF	
Total capacitance				31			
		$V_R = 650 \text{ V}, f = 1 \text{ MHz}$	z, T _j = 25 °C		29		

Thermal Characteristics

Thermal resistance, junction - case

Mechanical Properties			
Mounting torque	M	0.6	Nm

 R_{thJC}

°C/W

3.4

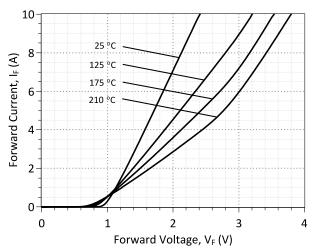


Figure 1: Typical Forward Characteristics

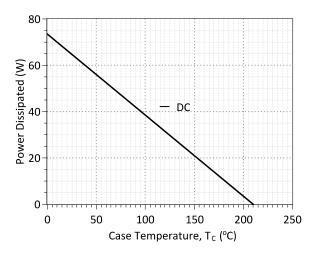


Figure 3: Power Derating Curve

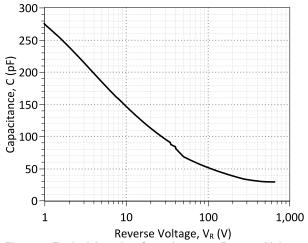


Figure 5: Typical Junction Capacitance vs Reverse Voltage Characteristics

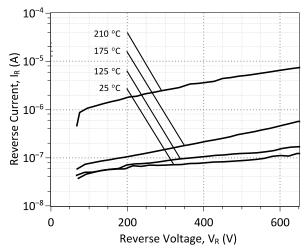


Figure 2: Typical Reverse Characteristics

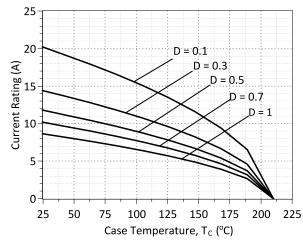


Figure 4: Current Derating Curves (D = t_P/T , t_P = 400 μ s) (Considering worst case Z_{th} conditions)

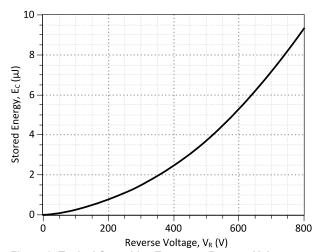


Figure 6: Typical Capacitive Energy vs Reverse Voltage Characteristics



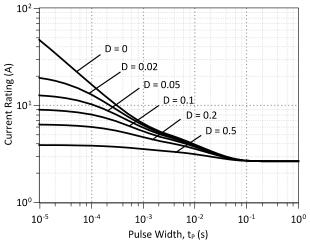


Figure 7: Current vs Pulse Duration Curves at T_c = 190 °C

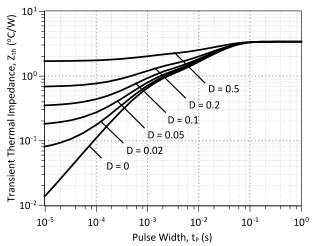
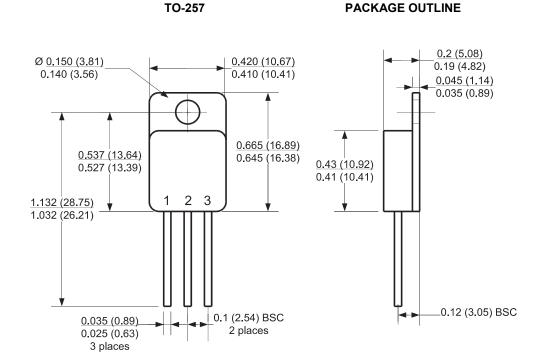
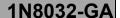


Figure 8: Transient Thermal Impedance

Package Dimensions:



- 1. CONTROLLED DIMENSION IS INCH. DIMENSION IN BRACKET IS MILLIMETER.
 2. DIMENSIONS DO NOT INCLUDE END FLASH, MOLD FLASH, MATERIAL PROTRUSIONS





Revision History					
Date	Revision	Comments	Supersedes		
2014/08/26	1	Updated Electrical Characteristics			
2012/04/24	0	Initial release			

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SPICE Model Parameters

Copy the following code into a SPICE software program for simulation of the 1N8032-GA device.

```
MODEL OF GeneSiC Semiconductor Inc.
     $Revision: 1.0
     $Date: 05-SEP-2013
    GeneSiC Semiconductor Inc.
    43670 Trade Center Place Ste. 155
    Dulles, VA 20166
    http://www.genesicsemi.com/index.php/hit-sic/schottky
    COPYRIGHT (C) 2013 GeneSiC Semiconductor Inc.
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* These models are provided "AS IS, WHERE IS, AND WITH NO WARRANTY
* OF ANY KIND EITHER EXPRESSED OR IMPLIED, INCLUDING BUT NOT LIMITED
* TO ANY IMPLIED WARRANTIES OF MERCHANTABILITY AND FITNESS FOR A
* PARTICULAR PURPOSE."
* Models accurate up to 2 times rated drain current.
* Start of 1N8032-GA SPICE Model
.SUBCKT 1N8032 ANODE KATHODE
D1 ANODE KATHODE 1N8032 25C; Call the Schottky Diode Model
D2 ANODE KATHODE 1N8032 PIN; Call the PiN Diode Model
.MODEL 1N8032 25C D
+ IS
     1.99E-17
                                    0.12463
                          RS
         1
                                    569.082
+ N
                          IKF
+ EG
         1.2
                         XTI
                                    3
+ TRS1
         0.0035
                         TRS2
                                    3.87E-05
                        VJ
         3.38E-10
                                    0.41772
+ CJO
         1.5479
                                    0.5
+ M
                         FC
+ TT
         1.00E-10
                         BV
                                    650
          1.00E-03
                          VPK
                                     650
+ IBV
          5
+ IAVE
                          TYPE
                                    SiC Schottky
      GeneSiC_Semiconductor
+ MFG
.MODEL 1N8032 PIN D
+ IS 1.33E-10
                        RS
                                    0.31147
+ N
          5
                          IKF
                                    0
+ EG
         3.23
                         XTI
                                    -10
+ FC
         0.5
                         TT
+ BV
         650
                          IBV
                                    1.00E-03
         650
+ VPK
                          IAVE
+ TYPE
          SiC PiN
.ENDS
```

^{*} End of 1N8032-GA SPICE Model

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LTP SK34B-TP SS3003CH-TL-E GA01SHT18 CRS10I30A(TE85L,QM MA4E2501L-1290 MBRB30H30CT-1G SB007-03C-TB-E

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ACDBA1200-HF ACDBA140-HF ACDBA2100-HF ACDBA3100-HF CDBQC0530L-HF CDBQC0240LR-HF ACDBA260LR-HF

ACDBA1100-HF SK310B-TP MA4E2502L-1246 MA4E2502H-1246 NRVBM120ET1G NSR01L30MXT5G SB560 PMAD1108-LF

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